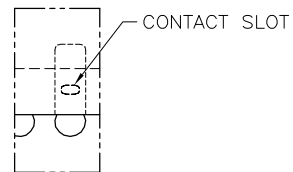
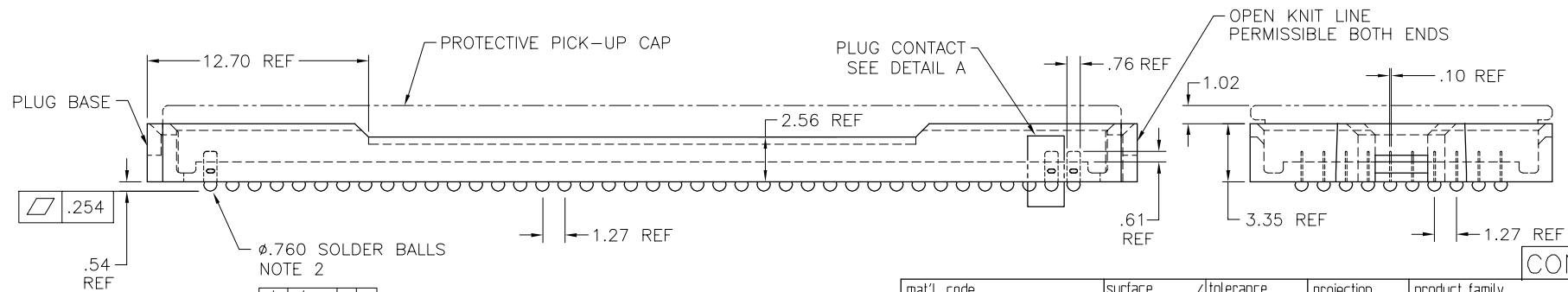
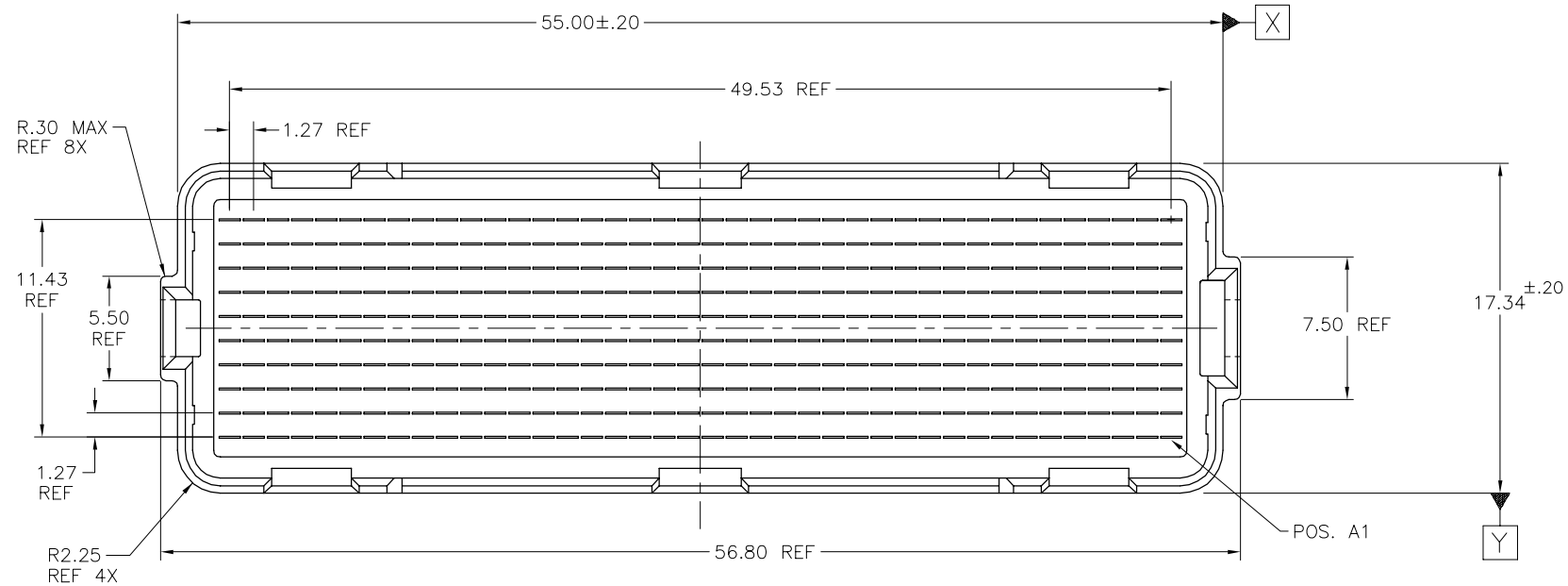
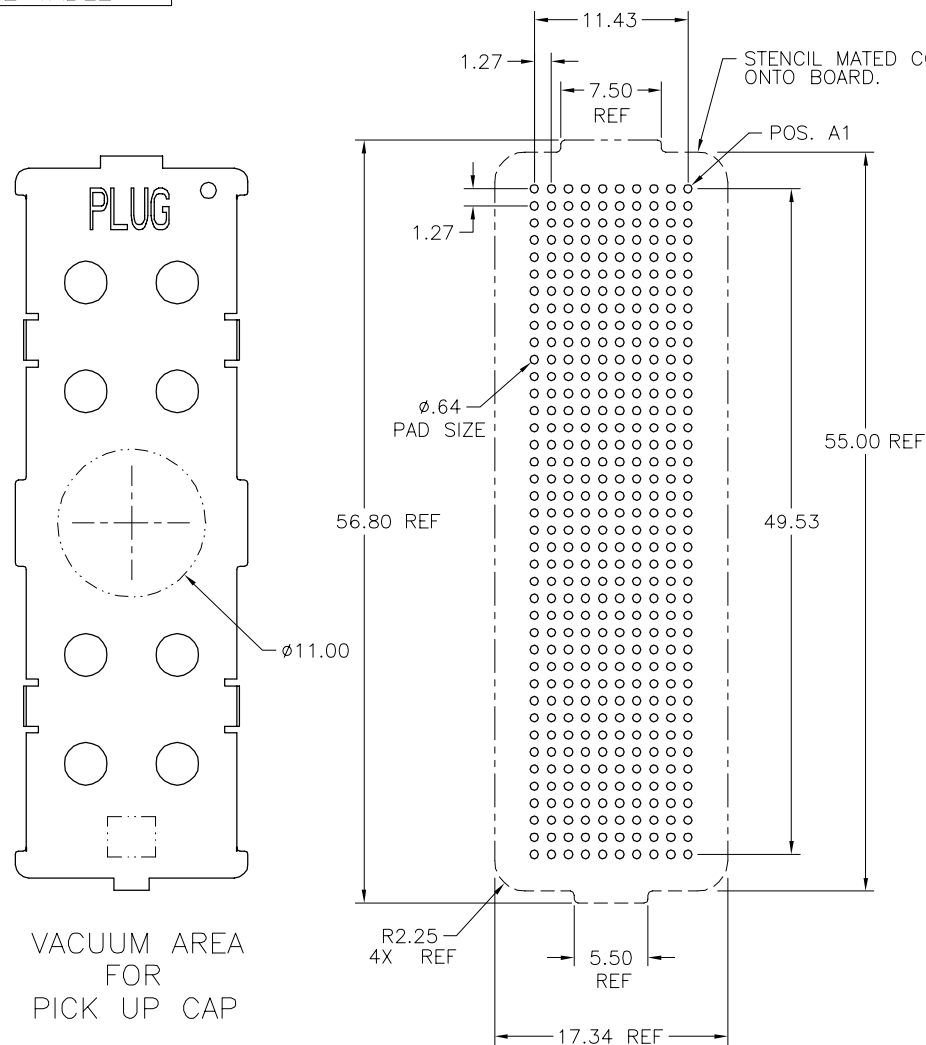


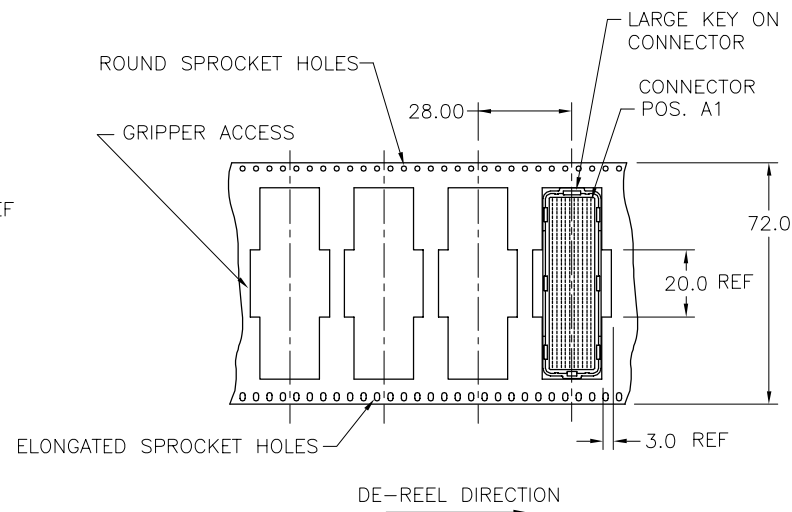
PRODUCT NUMBER
SEE TABLE



DETAIL A
SCALE 6:1

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY													
lir		ecn no		dr		date		tolerances unless otherwise specified						title									
A		V05-0324		DAI		04/19/05		angles		mm		0mm PLUG ASSY											
B		V06-0560		LP		2006/07/18		parallel				10 x 40 = 400 POS.											
C		V08-0084		LP		2008-03-18		± .02		scale 3:1													
								dr		D.INGRAM								8/24/04					
								engr		D.HARPER								8/24/04					
								chr		D.HARPER								8/24/04					
								appd		D.HARPER								8/24/04					
sheet index		revision sheet		C		C		C															
				1		2		3															

PRODUCT NUMBER
 SEE TABLE

 VACUUM AREA
 FOR
 PICK UP CAP

 BOARD PATTERN
 SCALE 2/1

 TAPE & REEL PACKAGING SCALE NONE
 PER EIA 481-3

CONFIDENTIAL

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY	
ltr	ec'n no	dr	date	tolerances unless otherwise specified		mm 	title	
c				angles	linear		0mm PLUG ASSY.	
				0° ±2°	XXX ±0.01		10x40= 400 POS.	
				dr	D.INGRAM	8/24/04	dwg no	sheet 2 of
				engr	D.HARPER	8/24/04	10043857	A4
				chr	D.HARPER	8/24/04	type	
				appd	D.HARPER	8/24/04	CUSTOMER Drawing	
sheet index	revision sheet							

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
10043857-102	YES	30u"(0.76um) Au OVER Ni	SnPb
10043857-102LF			SnAgCu LEAD FREE ⑥⑦
10043857-202	YES	SEE MATED HEIGHT TABLE (BELOW)	SnPb
10043857-202LF			SnAgCu LEAD FREE ⑥⑦

NOTES:

①. MAT'L:

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET3)
SOLDER BALL: (SEE TABLE ON SHEET3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

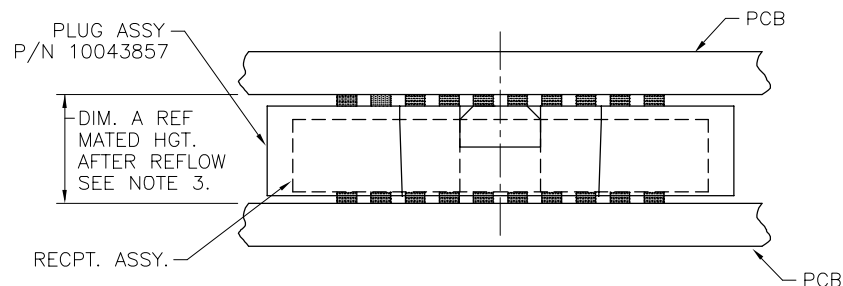
③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④. PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).

⑤. PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.

⑥. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

⑦. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	RECPT. ASSY. P/N	-2XX PLATING
4.0	74221	SEE NOTE 4
6.0	74388	SEE NOTE 5
8.0	74390	SEE NOTE 5

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

CONFIDENTIAL

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY					
ltr	ecr no	dr	date	tolerances unless otherwise specified						 scale 2:1		title			
c				angles		linear		0mm PLUG ASSY.							
								10x40= 400 POS.							
				0° ±2'		XXX ±.051									
				dr	D.INGRAM		8/24/04				dwg no		sheet 3 of		size
				engr	D.HARPER		8/24/04				10043857		A		
				chr	D.HARPER		8/24/04								
				appd	D.HARPER		8/24/04								
sheet index		revision sheet													